

HFM301-Q1 THRU HFM307-Q1

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HFM301-Q1 THRU HFM307-Q1

3.0A Surface Mount High Efficiency Rectifiers 50V-1000V

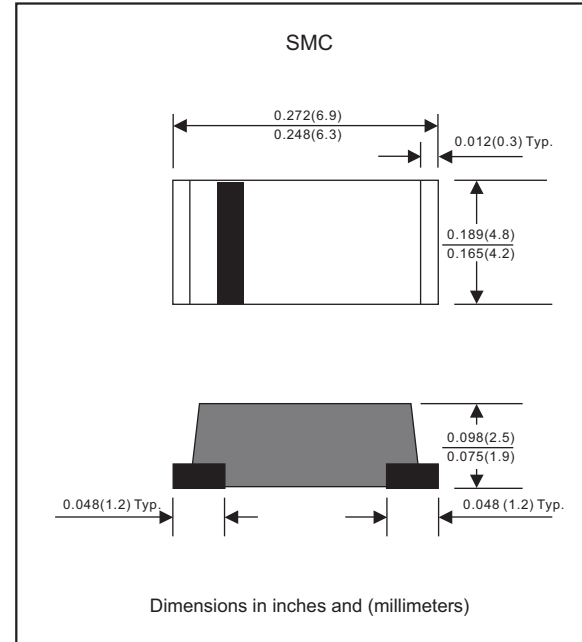
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance
- Low profile surface mounted application in order to optimize board space
- High current capability
- Ultrafast recovery time for high efficiency
- High surge current capability
- Glass passivated chip junction
- Lead-free parts meet RoHS requirements
- Qualified to AEC-Q101 standards for high reliability
- Suffix "-H" indicates Halogen free parts, ex. HFM301-Q1-H

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SMC
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.19 gram

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	HFM301-Q1	HFM302-Q1	HFM303-Q1	HFM304-Q1	HFM305-Q1	HFM306-Q1	HFM307-Q1	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum continuous reverse voltage	V_R	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I_o	3.0							A
Non-repetitive peak forward surge current 8.3ms single half sine-wave	I_{FSM}	100							A
Typical junction capacitance (Note 1)	C_J	70							pF
Operating junction temperature range	T_J	-55 to +150							$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-65 to +175							$^{\circ}\text{C}$

Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	HFM301-Q1	HFM302-Q1	HFM303-Q1	HFM304-Q1	HFM305-Q1	HFM306-Q1	HFM307-Q1	UNIT	
Maximum instantaneous forward voltage at $I_F=3.0\text{A}$	V_F	1.00			1.30	1.70			V	
Maximum reverse leakage current $T_J=25^{\circ}\text{C}$ at rated V_R $T_J=125^{\circ}\text{C}$	I_R	5.0 300							μA μA	
Maximum reverse recovery time (Note 2)	t_{rr}	50				75				ns

Thermal characteristics

PARAMETER	SYMBOLS	HFM301-Q1	HFM302-Q1	HFM303-Q1	HFM304-Q1	HFM305-Q1	HFM306-Q1	HFM307-Q1	UNIT
Typical thermal resistance junction to ambient (Note 3)	$R_{\theta JA}$	48							$^{\circ}\text{C}/\text{W}$
Typical thermal resistance junction to case (Note 3)	$R_{\theta JC}$	33							$^{\circ}\text{C}/\text{W}$

Notes 1: Measured at 1 MHz and applied reverse voltage of 4.0 VDC
 2: Measured with $I_F = 0.5\text{A}$, $I_R = 1\text{A}$, $I_{rr} = 0.25\text{A}$
 3: Mounted on FR-4 PCB Copper, minimum recommended pad layout

Rating and characteristic curves (HFM301-Q1 THRU HFM307-Q1)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

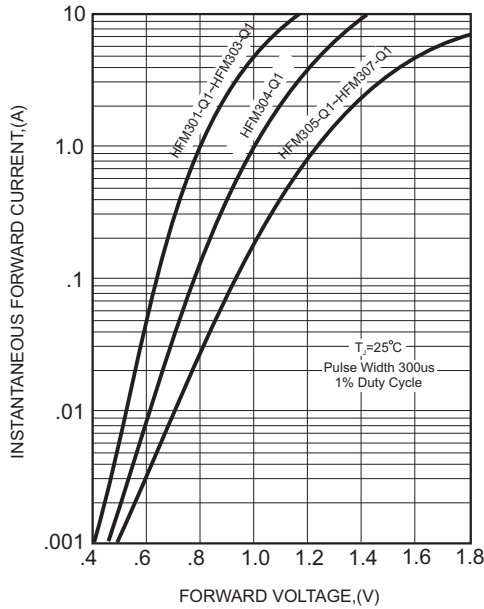


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

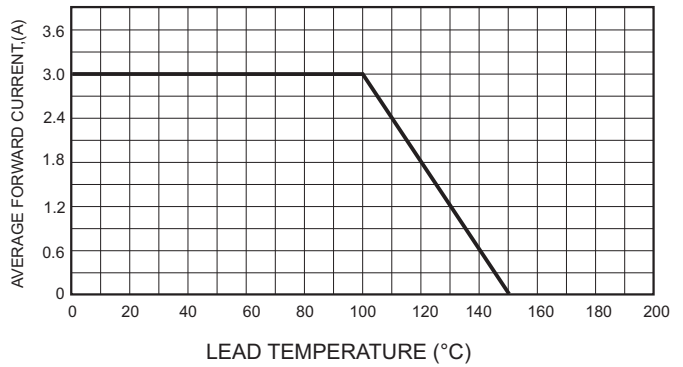


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

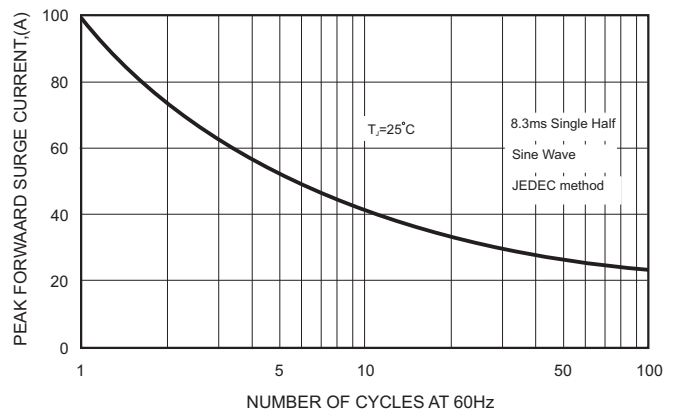
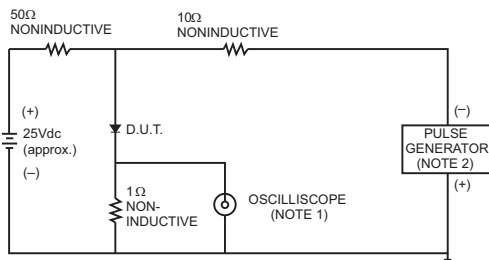


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



- NOTES: 1. Rise Time = 7ns max., Input Impedance = 1 megohm, 22pF.
2. Rise Time = 10ns max., Source Impedance = 50 ohms.

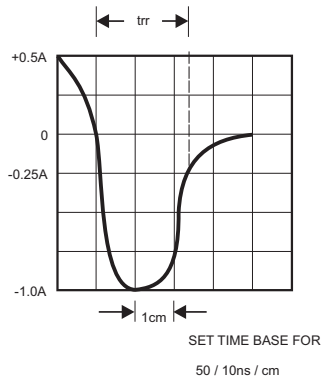
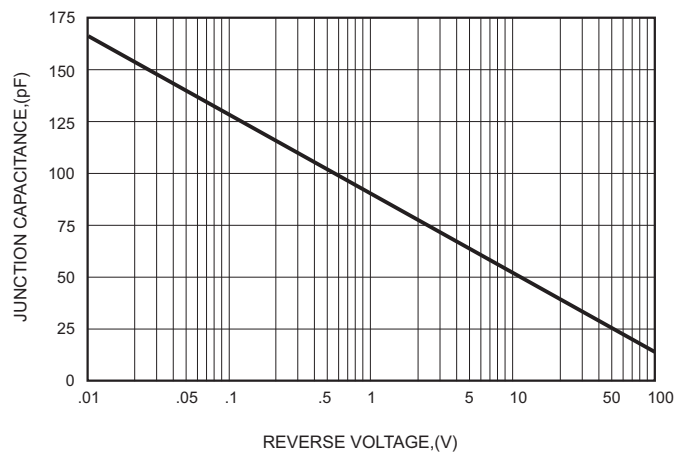




FIG.5-TYPICAL JUNCTION CAPACITANCE



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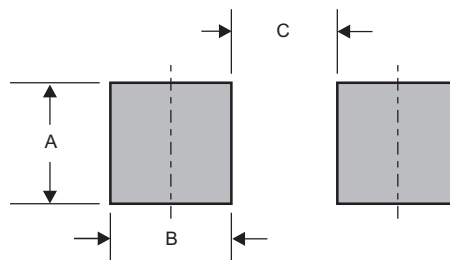
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
HFM301-Q1	H31
HFM302-Q1	H32
HFM303-Q1	H33
HFM304-Q1	H34
HFM305-Q1	H35
HFM306-Q1	H36
HFM307-Q1	H37

Suggested solder pad layout

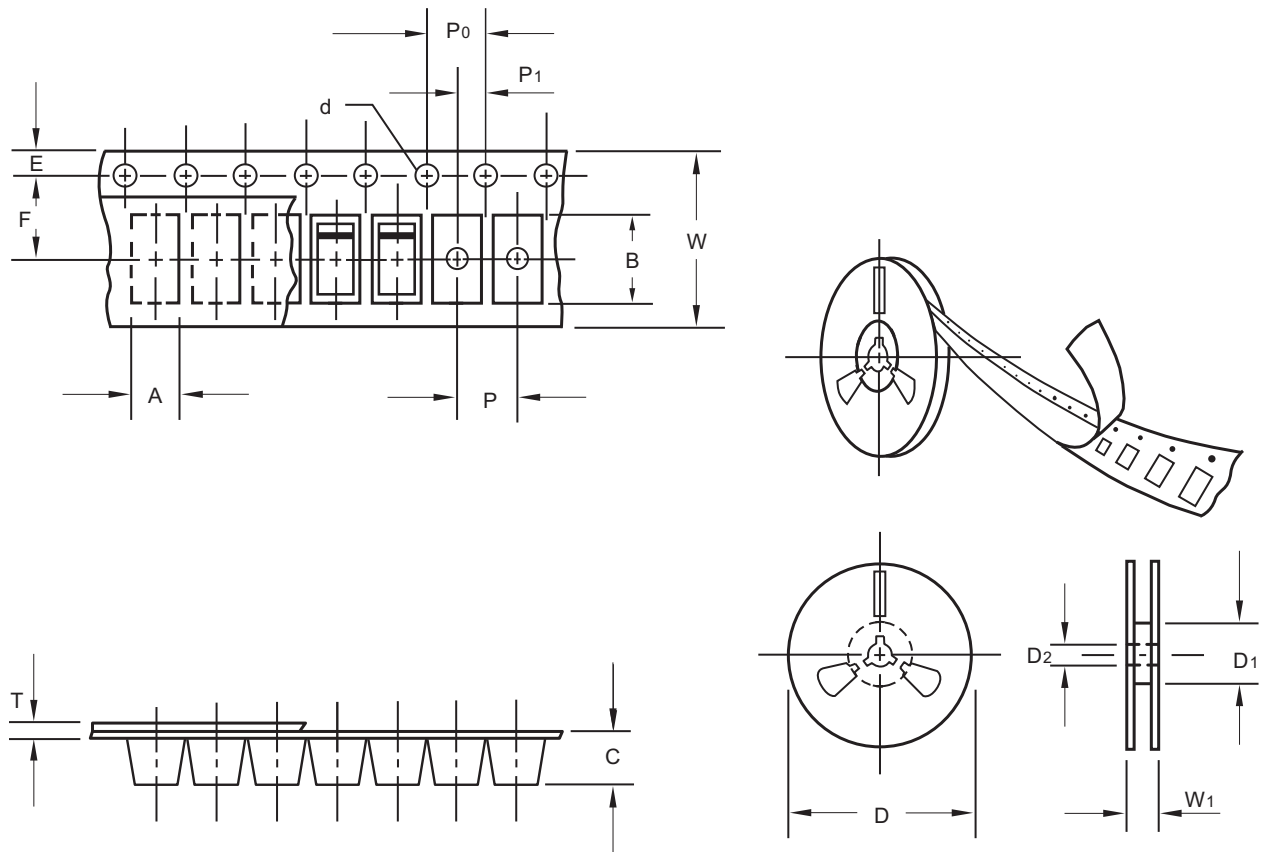


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMC	0.189 (4.80)	0.063 (1.60)	0.158 (4.00)

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Packing information



unit:mm

Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	5.10
Carrier length	B	0.1	7.20
Carrier depth	C	0.1	2.50
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

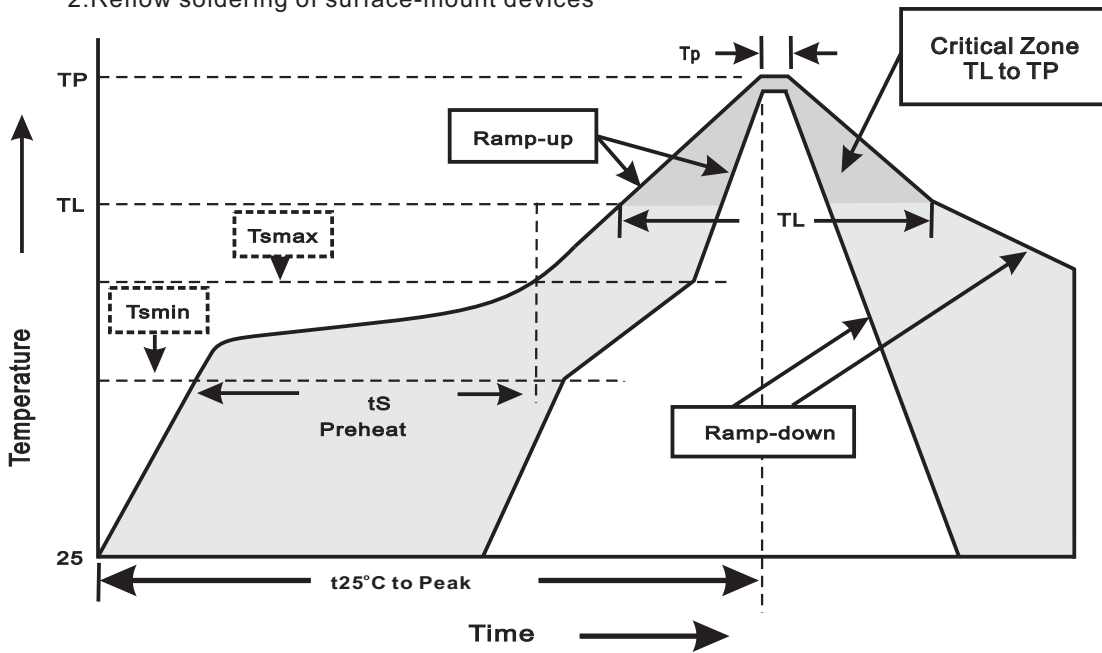
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	8.0	6,000	335*335*38	330	350*330*360	48,000	17.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. MSL Preconditioning	24hr bake@125°C+168hrs@85°C /85%RH+3xIR@260°C+1flux immersion+alcohol+DI H2O rinse	JESD22-A113
2. Operation Life	Ta=25°C,Rated Current (Io=Io max.)Test Duration:1000hrs	MIL-STD-750E METHOD 1027.3
3. High Temperature Reverse Bias	80% Rated VR (Tj=Tj max.)Test Duration:1000hrs	JESD22-A108
4. High Temperature Storage Life	Ta=125°C Test Duration:1000hrs	JESD22 A-103
5. Temperature Cycle	-55°C(15min) to 150°C(15min)Test Cycles:1000cycles	JESD22 A-104
6. Autoclave	P=2atm Ta=121°C RH=100% Test Duration:96hrs	JESD22 A-102
7. Intermittent Operational Life	Ta=25°C,On/Io Max. 2min, Off/2min, Test Cycles:15000cycles	MIL-STD-750E METHOD 1037
8. Solderability	245±5°C for 5sec	J-STD-002
9. Moisture Resistance	Ta=85°C/85% Relative humidity Test Duration:1000hrs	MIL-STD-750E METHOD 1021.2
10. Resistance To Solder Heat	260±5°C for 10sec	JESD22 B-106
11. High Temperature High Humidity Reverse Bias	Ta=85°C, 85%RH, with device reverse biased at 80% of rated breakdown voltage up to a maximum of 100V or limit of chamber Test Duration:1000hrs	JESD22-A101